

LIST OF DOCUMENTS CITED BY APPLICANT  
(Use several sheets if necessary)ATTY. DOCKET NO.  
01 P 7422 US 01SERIAL NO.  
TBDJ1031 U.S. PTC  
09/854760  
05/14/01APPLICANT  
Xian J. NingFILING DATE  
May 14, 2001GROUP  
TBD

## U.S. PATENT DOCUMENTS

*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE (IF APPROPRIATE)
	AA						
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						

## FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							VIS	SO
	AL							
	AM							
	AN							

## OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

LV	AO	Chi-Tzung Wang, et al., Pad Wear Analysis in CMP; 1999 VMIC Conference; 1999 IMIC 109/99/0267(c)
LV	AP	Sriini Raghavan, et al., Electrochemical Behavior of Copper and Tantalum in Silica Slurries Containing Hydroxylamine, 1999 VMIC Conference; 1999 IMIC 109/99/0619(c)
LV	AQ	Rajeev Bajaj, et al., Manufacturability Considerations and Approaches for Development of a Copper CMP Process; 1999 VMIC Conference; 1999 IMIC 109/99/0144(c)

THIS FORM IS FOR USE IN THE UNITED STATES ONLY. IT IS NOT TO BE USED IN THE INTERNATIONAL TRADE COMMISSION OR THE UNITED STATES COURT OF INTERNATIONAL TRADE. IT IS NOT TO BE USED IN CONFORMITY WITH THE TRADE AGREEMENTS OR THE TRADE POLICIES OF THE UNITED STATES.

DATE CONSIDERED: 12/4/2003

EXAMINER: LAN VINH

*Lan*